



# Product End-of-Life Disassembly Instructions

## Product Category: Networking Equipment

### Marketing Name / Model

[List multiple models if applicable.]

HP Flex Fabric 11900 2400W DC Power Supply(JG617A)

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	7
Batteries	All types including standard alkaline and lithium coin or button style batteries	
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	All of them on upper PCBA	20
External electrical cables and cords		0
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Philips Screw Driver	Medium
Wire cutter	Medium
Pliers	Medium

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. [Redacted]
2. [Redacted]
3. [Redacted]
4. [Redacted]

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

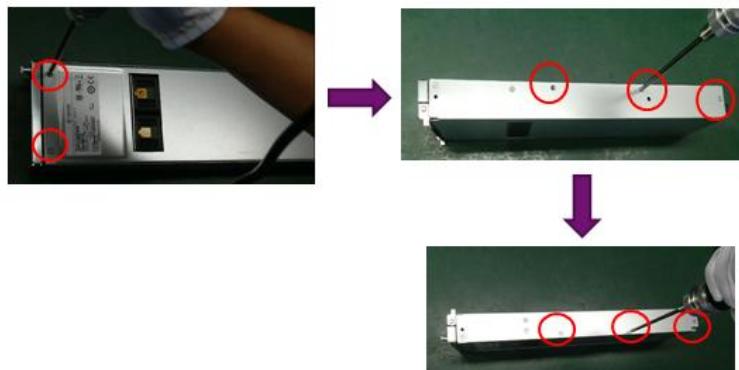


图1.



图2.



图3.



图4.



图5.

### 3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1	Fe	28.7	1.41%		Fe recycling	
2	Fe	31.06	0.9%		Fe recycling	
3	Al	315	10.23%		Al recycling	
4	Complex PWB	7for 101.5	14.4%	The surface If PCB is greater than 10 square centimeters		
5	Al	8.9	0.26%		Al recycling	
6	Be-Cu	4.4	0.13%		Cu recycling	
7	Fe	1643.5	62.6%		Fe recycling	
8	PC	2	0.08%		Pla recycling	

### 4. Revised record

Date	Version	Author	Modify content
2013.02.19	V0	Feng Junnan	Initial version